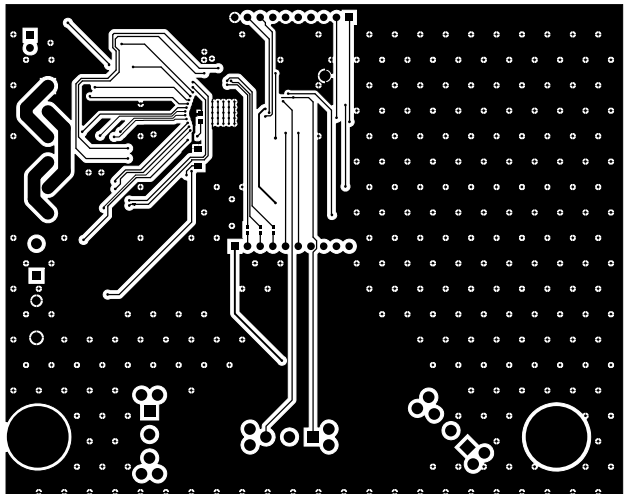
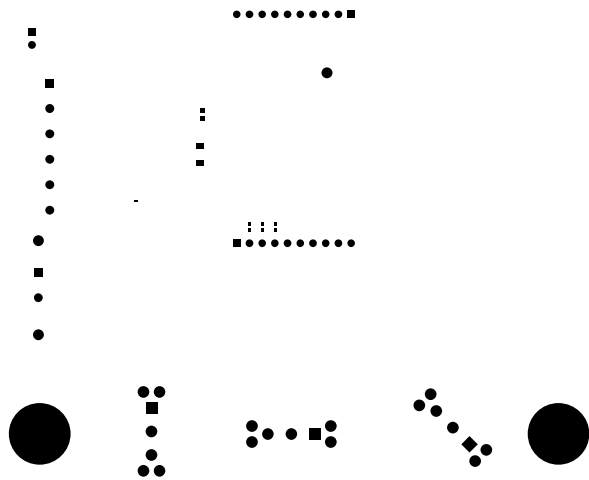
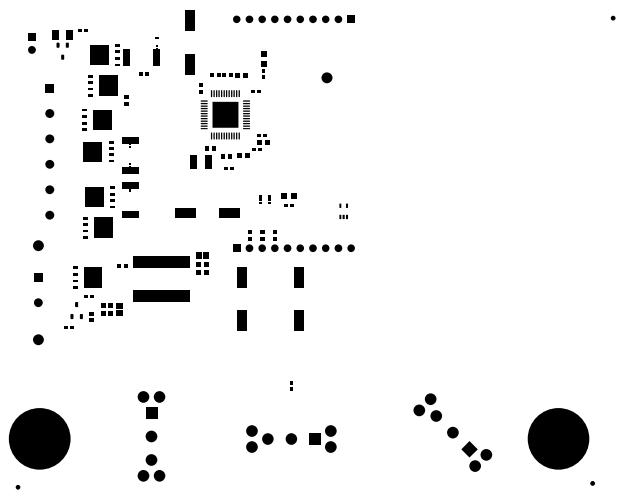


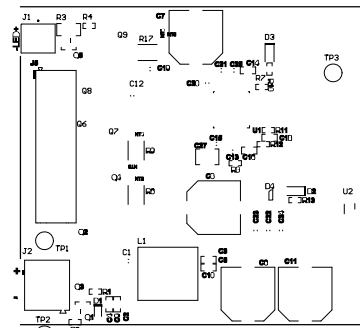
Top Layer



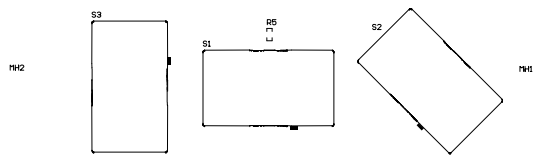
Bottom Layer



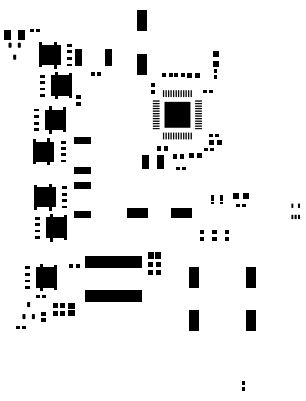




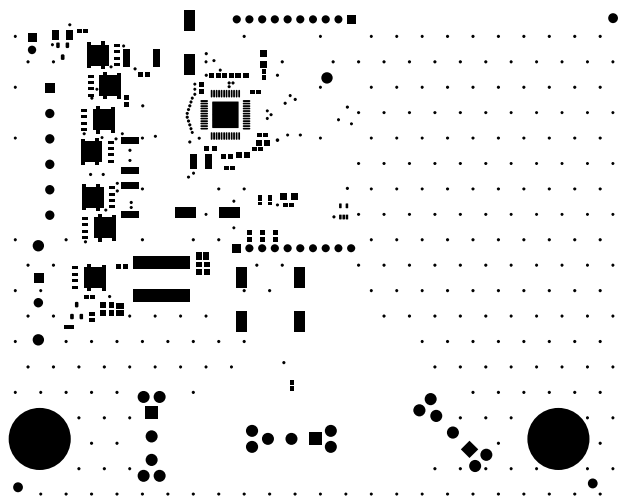
  
**TIDA-01330**  
Pb-Free



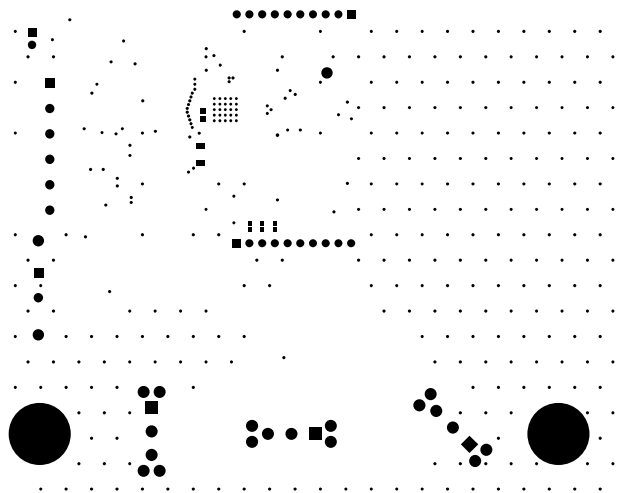
Top Overlay



Top Paste



Top Solder



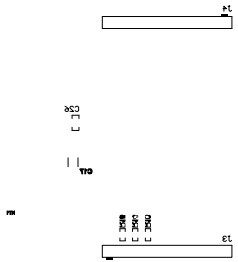
Bottom Solder



⋮

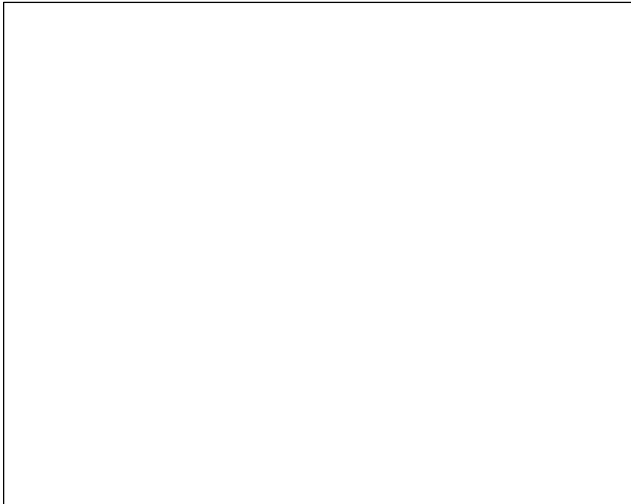
⋮⋮

Bottom Paste

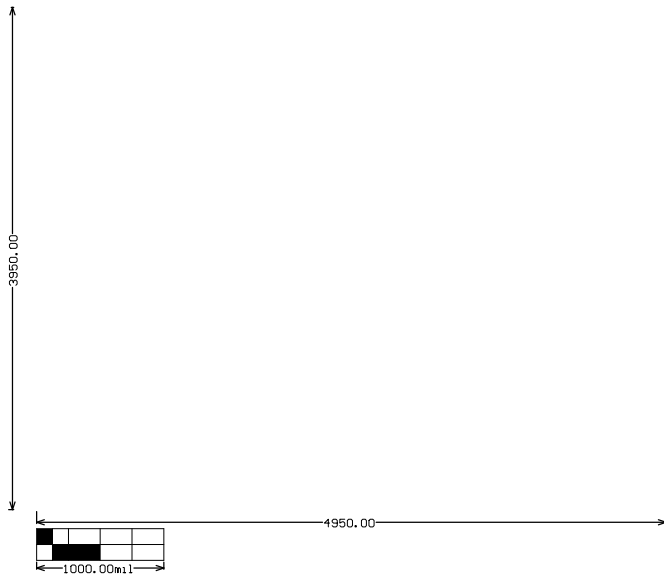


Bottom Overlay

Keep-Out Layer



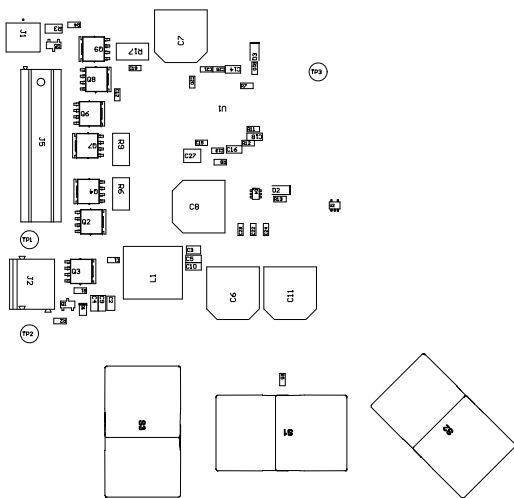
M1 Board Outline



M2 Board Dimensions

M3 3D STEP Top

M4 3D STEP Bottom



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01330	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01330		
PLOT NAME = TIDA-01330.GM5	GENERATED : 1/6/2017	10:44:27 AM	TEXAS INSTRUMENTS



11

52

51

50  
49  
48


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: IN0 Variants

PCB VIEWED FROM BOTTOM SIDE	REV: E1	BOARD # : TIDA-01330	SUM REV: Not In VersionControl
TID # :	TIDA-01330		
PLT NAME = TIDA-01330.GBR	GENERATED : 10:44:28 AM	TEXAS INSTRUMENTS	

	1	2	3	4	5	6	
A							A
B							B
C							C
D							D
	1	2	3	4	5	6	

M9 Title Sheet

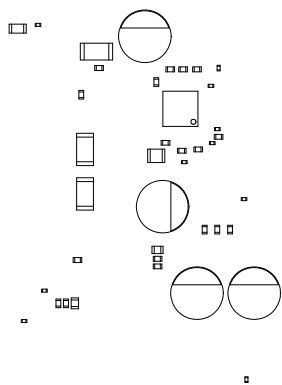
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PROJECT TITLE: Automotive 2-Axis Power Seat Driver	
DESIGNED FOR: Public Release	
FILE NAME: TIDA-01330.PcbDoc	
ENGINEER: Clark Kinnaird	LAYOUT BY:
SCALE: 1.00	ALTIM DESIGNER VERSION: 16.1.12.290

DESIGN INFORMATION	
MIN. TRACK WIDTH:	<u>8</u> MIL
MIN. CLEARANCE:	<u>0,2</u> mm
MIN. VIA PAD SIZE:	<u>24</u> MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- <u>5</u> MIL HOLES +/- <u>3</u> MIL HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- <u>3</u> MIL	
MATERIAL:	
<input type="checkbox"/> FR-408	<input checked="" type="checkbox"/> FR-4 High Tg <input type="checkbox"/> OTHER
THICKNESS:	<input checked="" type="checkbox"/> 62 MIL (1.6mm) +/-10% <input type="checkbox"/> OTHER
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/-
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/-
DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES
PTH COPPER THICKNESS:	<input checked="" type="checkbox"/> 20-30 um <input type="checkbox"/> OTHER
BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP <input checked="" type="checkbox"/> BOTTOM
SILKSCREEN COLOR:	<input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER
SOLDER RESIST COLOR:	<input checked="" type="checkbox"/> GREEN <input type="checkbox"/> OTHER <input checked="" type="checkbox"/> MATTE <input type="checkbox"/> SEMI-GLOSS
SURFACE FINISH:	<input checked="" type="checkbox"/> IMMERSION GOLD (ENIG) <input type="checkbox"/> ENEPG <input type="checkbox"/> IMM. TIN/SILVER OR EQUIV <input type="checkbox"/> OTHER
ARRAY/PANEL:	<input type="checkbox"/> CUT AND TRM PER M1 BOARD OUTLINE <input type="checkbox"/> N.C. ROUTE <input checked="" type="checkbox"/> V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS ->	<input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3 <input checked="" type="checkbox"/> RoHS <input type="checkbox"/> OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER	
ADDITIONAL REQUIREMENTS:	
MICROSECTION:	<input type="checkbox"/> YES
BARE BOARD ELEC. TEST:	<input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01330	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01330		
PLOT NAME = TIDA-01330.GM11	GENERATED : 1/6/2017	10:44:28 AM	TEXAS INSTRUMENTS

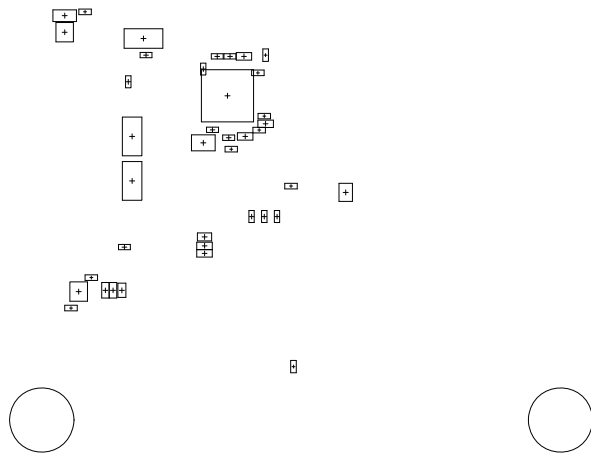
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



M13 Component Bodies Top

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M15 Courtyards Top



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M16 Courtyards Bottom

M17 Embedded Cavity

M18 Embedded Assembly

M19 Embedded Keepout

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